



Creative Materials, Inc.
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108-50

THERMALLY CONDUCTIVE, LOW STRESS EPOXY

DESCRIPTION: 108-50 is a one component, thermally conductive, low stress, low shrink potting compound and adhesive. 108-50 features *exceptional* resistance to thermal cycling. Recommended applications include potting of dissimilar materials requiring Class "F" service temperature rating. 108-50 can also be used as an adhesive for bonding stress sensitive substrates.

PROPERTIES:

Color	Grey
Viscosity (cps)	100,000-160,000 @ Room Temperature 30,000-50,000 @ 50°C
Dielectric Strength (volts/mil)	495
Volume Resistivity (Ω -cm)	1×10^{14}
Dielectric Constant (1 kHz)	4.4
Dielectric Factor (60 Hz)	0.012
Hardness (Shore D)	80 @ Room Temperature 35 @ 121°C
Thermal Conductivity (W/mK)	1.83

HANDLING & CURING INSTRUCTIONS: Material is ready to use as received. Store at low temperature to maintain consistent flow properties. Allow material to warm up to room temperature before opening container. Cure for two (2) hours at 150°C. (Note: Best properties are obtained when cured at 121°C for four hours.)

STORAGE: Shelf Life: 12 months at 0°C; or 6 weeks at 25°C; or 1 week at 40°C.

SAFETY & HANDLING: Use with adequate ventilation. Keep away from sparks and open flames. Avoid prolonged contact with skin and breathing of vapors. Wash with soap and water to remove from skin.

All technical information is based on data obtained by CMI personnel and is believed to be reliable. No warranty is either expressed or implied with respect to results or possible infringements on patents.

REVISION DATE: 2/6/09 REVISION: B